Microchip Technology - DSPIC33FJ32MC101-E/SO Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

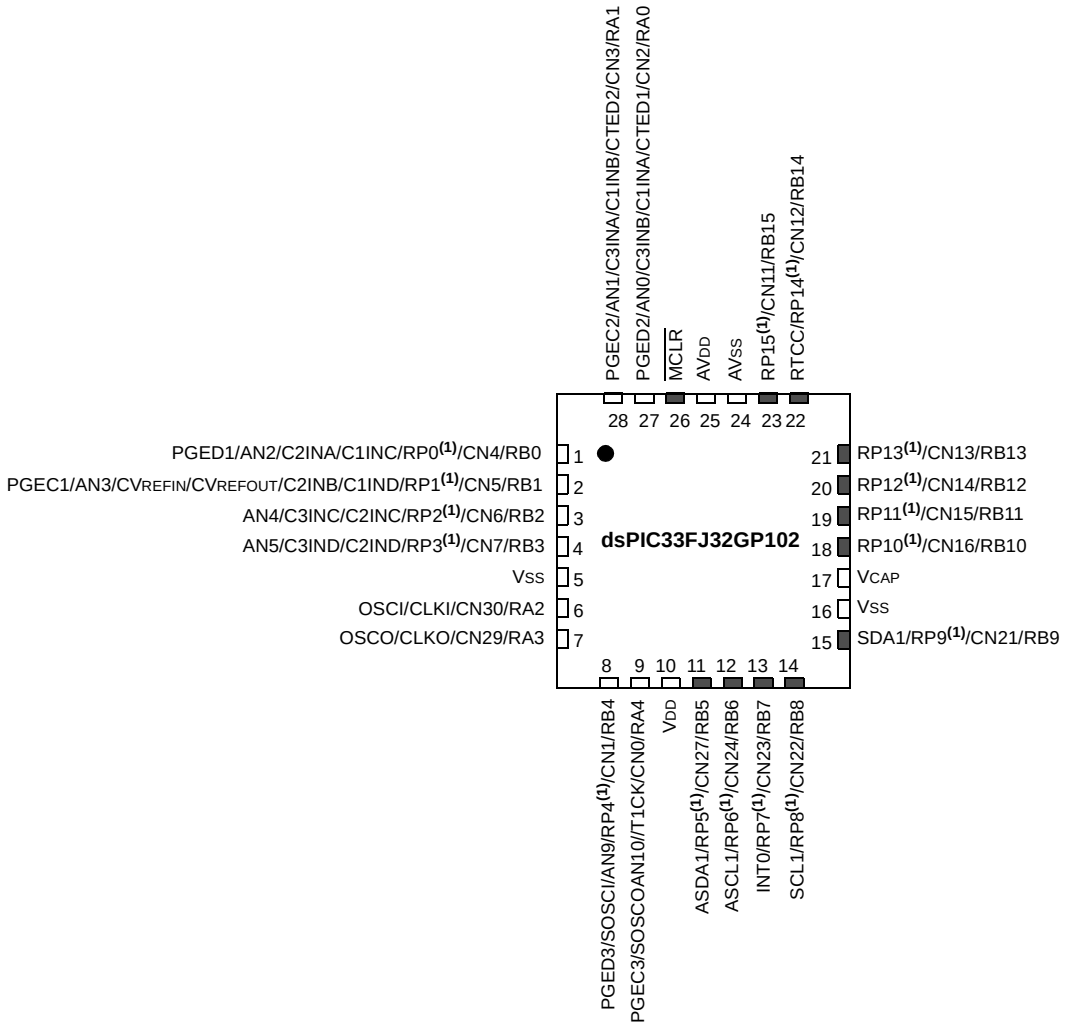
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	15
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32mc101-e-so

Pin Diagrams (Continued)

28-Pin QFN(2)

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Data Memory"** (DS70202) and **"Program Memory"** (DS70203) in the *"dsPIC33/PIC24 Family Reference Manual"*, which are available from the Microchip web site (www.microchip.com).

The device architecture features separate program and data memory spaces and buses. This architecture also allows the direct access of program memory from the data space during code execution.

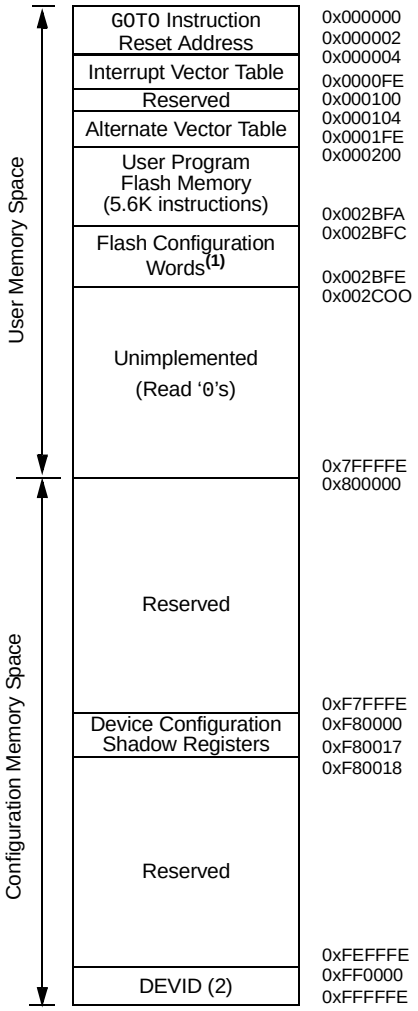
4.1 Program Address Space

The program address memory space of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit Program Counter (PC) during program execution, or from table operation or data space remapping as described in **Section 4.6 "Interfacing Program and Data Memory Spaces"**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

The memory maps for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family of devices are shown in Figure 4-1 and Figure 4-2.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33FJ16(GP/MC)101/102 DEVICES



Note 1: On Reset, these bits are automatically copied into the device Configuration Shadow registers.

4.2.5 X AND Y DATA SPACES

The core has two data spaces, X and Y. These data spaces can be considered either separate (for some DSP instructions), or as one unified linear address range (for MCU instructions). The data spaces are accessed using two Address Generation Units (AGUs) and separate data paths. This feature allows certain instructions to concurrently fetch two words from RAM, thereby enabling efficient execution of DSP algorithms such as Finite Impulse Response (FIR) filtering and Fast Fourier transform (FFT).

The X data space is used by all instructions and supports all addressing modes. X data space has separate read and write data buses. The X read data bus is the read data path for all instructions that view data space as combined X and Y address space. It is also the X data prefetch path for the dual operand DSP instructions (MAC class).

The Y data space is used in concert with the X data space by the MAC class of instructions (CLR, ED, EDAC, MAC, MOVSAC, MPY, MPY.N and MSC) to provide two concurrent data read paths.

Both the X and Y data spaces support Modulo Addressing mode for all instructions, subject to addressing mode restrictions. Bit-Reversed Addressing mode is only supported for writes to X data space.

All data memory writes, including in DSP instructions, view data space as combined X and Y address space. The boundary between the X and Y data spaces is device-dependent and is not user-programmable.

All Effective Addresses are 16 bits wide and point to bytes within the data space. Therefore, the data space address range is 64 Kbytes, or 32K words, although the implemented memory locations vary by device.

8.3 Clock Switching Operation

Applications are free to switch among any of the four clock sources (Primary, LP, FRC and LPRC) under software control at any time. To limit the possible side effects of this flexibility, dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices have a safeguard lock built into the switch process.

Note:	Primary Oscillator mode has three different submodes (MS, HS and EC), which are determined by the POSCMD<1:0> Configuration bits. While an application can switch to and from Primary Oscillator mode in software, it cannot switch among the different primary submodes without reprogramming the device.

8.3.1 ENABLING CLOCK SWITCHING

To enable clock switching, the FCKSM1 Configuration bit in the FOSC Configuration register must be programmed to '0'. (Refer to **Section 23.1 "Configuration Bits"** for further details.) If the FCKSM1 Configuration bit is unprogrammed ('1'), the clock switching function and Fail-Safe Clock Monitor function are disabled. This is the default setting.

The NOSCx control bits (OSCCON<10:8>) do not control the clock selection when clock switching is disabled. However, the COSCx bits (OSCCON<14:12>) reflect the clock source selected by the FNOSCx Configuration bits.

The OSWEN control bit (OSCCON<0>) has no effect when clock switching is disabled; it is held at '0' at all times.

8.3.2 OSCILLATOR SWITCHING SEQUENCE

Performing a clock switch requires this basic sequence:

1. If desired, read the COSC bits (OSCCON<14:12>) to determine the current oscillator source.
2. Perform the unlock sequence to allow a write to the OSCCON register high byte.
3. Write the appropriate value to the NOSCx control bits (OSCCON<10:8>) for the new oscillator source.
4. Perform the unlock sequence to allow a write to the OSCCON register low byte.
5. Set the OSWEN bit (OSCCON<0>) to initiate the oscillator switch.

Once the basic sequence is completed, the system clock hardware responds automatically as follows:

1. The clock switching hardware compares the COSCx status bits with the new value of the NOSCx control bits. If they are the same, the clock switch is a redundant operation. In this case, the OSWEN bit is cleared automatically and the clock switch is aborted.
2. If a valid clock switch has been initiated, the LOCK and CF (OSCCON<5,3>) status bits are cleared.
3. The new oscillator is turned on by the hardware if it is not currently running. If a crystal oscillator must be turned on, the hardware waits until the Oscillator Start-up Timer (OST) expires. If the new source is using the PLL, the hardware waits until a PLL lock is detected (LOCK = 1).
4. The hardware waits for 10 clock cycles from the new clock source and then performs the clock switch.
5. The hardware clears the OSWEN bit to indicate a successful clock transition. In addition, the NOSCx bit values are transferred to the COSCx status bits.
6. The old clock source is turned off at this time, with the exception of LPRC (if WDT or FSCM is enabled) or LP (if LPOSCEN remains set).

Note 1:	The processor continues to execute code throughout the clock switching sequence. Timing-sensitive code should not be executed during this time.
2:	Direct clock switches between any Primary Oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.
3:	Refer to **"Oscillator (Part VI)"** (DS70644) in the *"dsPIC33/PIC24 Family Reference Manual"* for details.

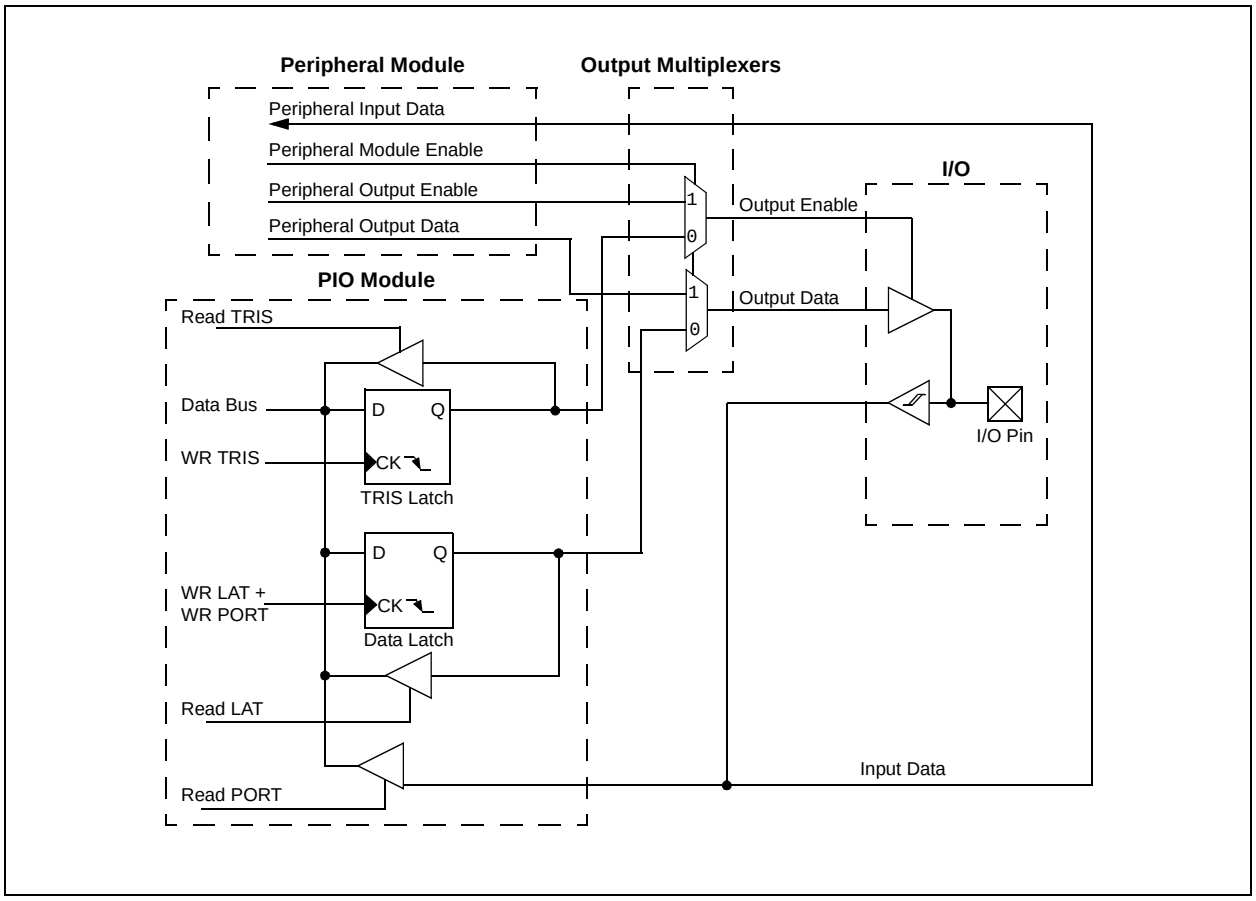
8.4 Fail-Safe Clock Monitor (FSCM)

The Fail-Safe Clock Monitor (FSCM) allows the device to continue to operate even in the event of an oscillator failure. The FSCM function is enabled by programming. If the FSCM function is enabled, the LPRC internal oscillator runs at all times (except during Sleep mode) and is not subject to control by the Watchdog Timer.

In the event of an oscillator failure, the FSCM generates a clock failure trap event and switches the system clock over to the FRC oscillator. Then, the application program can either attempt to restart the oscillator or execute a controlled shutdown. The trap can be treated as a Warm Reset by simply loading the Reset address into the oscillator fail trap vector.

If the PLL multiplier is used to scale the system clock, the internal FRC is also multiplied by the same factor on clock failure. Essentially, the device switches to FRC with PLL on a clock failure.

FIGURE 10-1: BLOCK DIAGRAM OF A TYPICAL SHARED PORT STRUCTURE



14.0 OUTPUT COMPARE

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Output Compare"** (DS70209) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

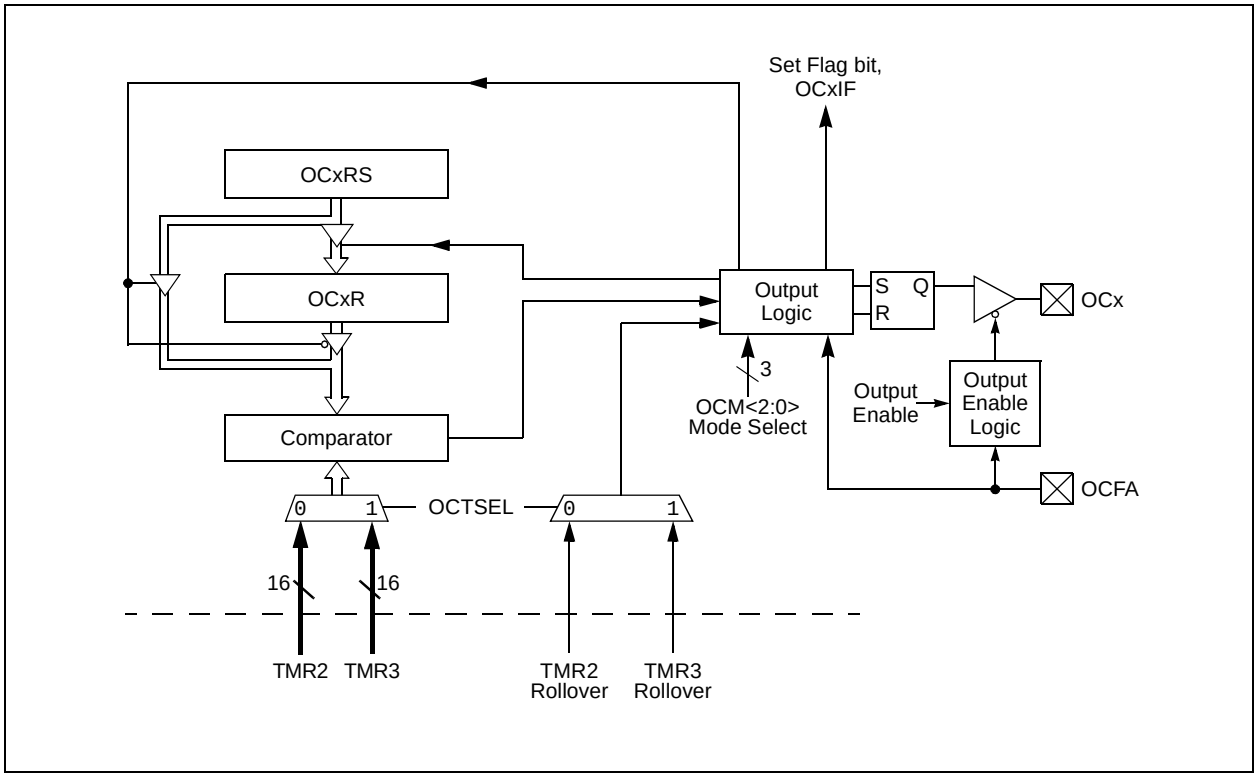
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The output compare module can select either Timer2 or Timer3 for its time base. The module compares the value of the timer with the value of one or two compare registers depending on the operating mode selected. The state of the output pin changes when the timer value matches the Output Compare Control register value. The output compare module generates either a single output pulse, or a sequence of output pulses, by changing the state of the output pin on the compare match events. The output compare module can also generate interrupts on compare match events.

The output compare module has multiple operating modes:

- Active-Low One-Shot mode
- Active-High One-Shot mode
- Toggle mode
- Delayed One-Shot mode
- Continuous Pulse mode
- PWM mode without Fault Protection
- PWM mode with Fault Protection

FIGURE 14-1: OUTPUT COMPARE x MODULE BLOCK DIAGRAM



REGISTER 15-9: PxFLTACON: PWMx FAULT A CONTROL REGISTER(1,2,3,4)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	FAOV3H	FAOV3L	FAOV2H	FAOV2L	FAOV1H	FAOV1L
bit 15							bit 8

R/W-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
FLTAM	—	—	—	—	FAEN3	FAEN2	FAEN1
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **FAOV<3:1>H:FAOV<3:1>L:** Fault Input A PWMx Override Value bits
1 = The PWMx output pin is driven active on an external Fault input event
0 = The PWMx output pin is driven inactive on an external Fault input event

bit 7 **FLTAM:** Fault A Mode bit
1 = The Fault A input pin functions in the Cycle-by-Cycle mode
0 = The Fault A input pin latches all control pins to the programmed states in PxFLTACON<13:8>

bit 6-3 **Unimplemented:** Read as '0'

bit 2 **FAEN3:** Fault Input A Enable bit
1 = PWMxH3/PWMxL3 pin pair is controlled by Fault Input A
0 = PWMxH3/PWMxL3 pin pair is not controlled by Fault Input A

bit 1 **FAEN2:** Fault Input A Enable bit
1 = PWMxH2/PWMxL2 pin pair is controlled by Fault Input A
0 = PWMxH2/PWMxL2 pin pair is not controlled by Fault Input A

bit 0 **FAEN1:** Fault Input A Enable bit
1 = PWMxH1/PWMxL1 pin pair is controlled by Fault Input A
0 = PWMxH1/PWMxL1 pin pair is not controlled by Fault Input A

Note 1: Comparator outputs are not internally connected to the PWM Fault control logic. If using the comparator modules for Fault generation, the user must externally connect the desired comparator output pin to the dedicated $\overline{\text{FLTA1}}$ or $\overline{\text{FLTB1}}$ input pin.

2: Refer to Table 15-1 for $\overline{\text{FLTA1}}$ implementation details.

3: The PxFLTACON register is a write-protected register. Refer to **Section 15.3 "Write-Protected Registers"** for more information on the unlock sequence.

4: During any Reset event, $\overline{\text{FLTA1}}$ is enabled by default and must be cleared as described in **Section 15.2 "PWM Faults"**.

20.0 COMPARATOR MODULE

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 device families. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Comparator with Blanking"** (DS70647) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

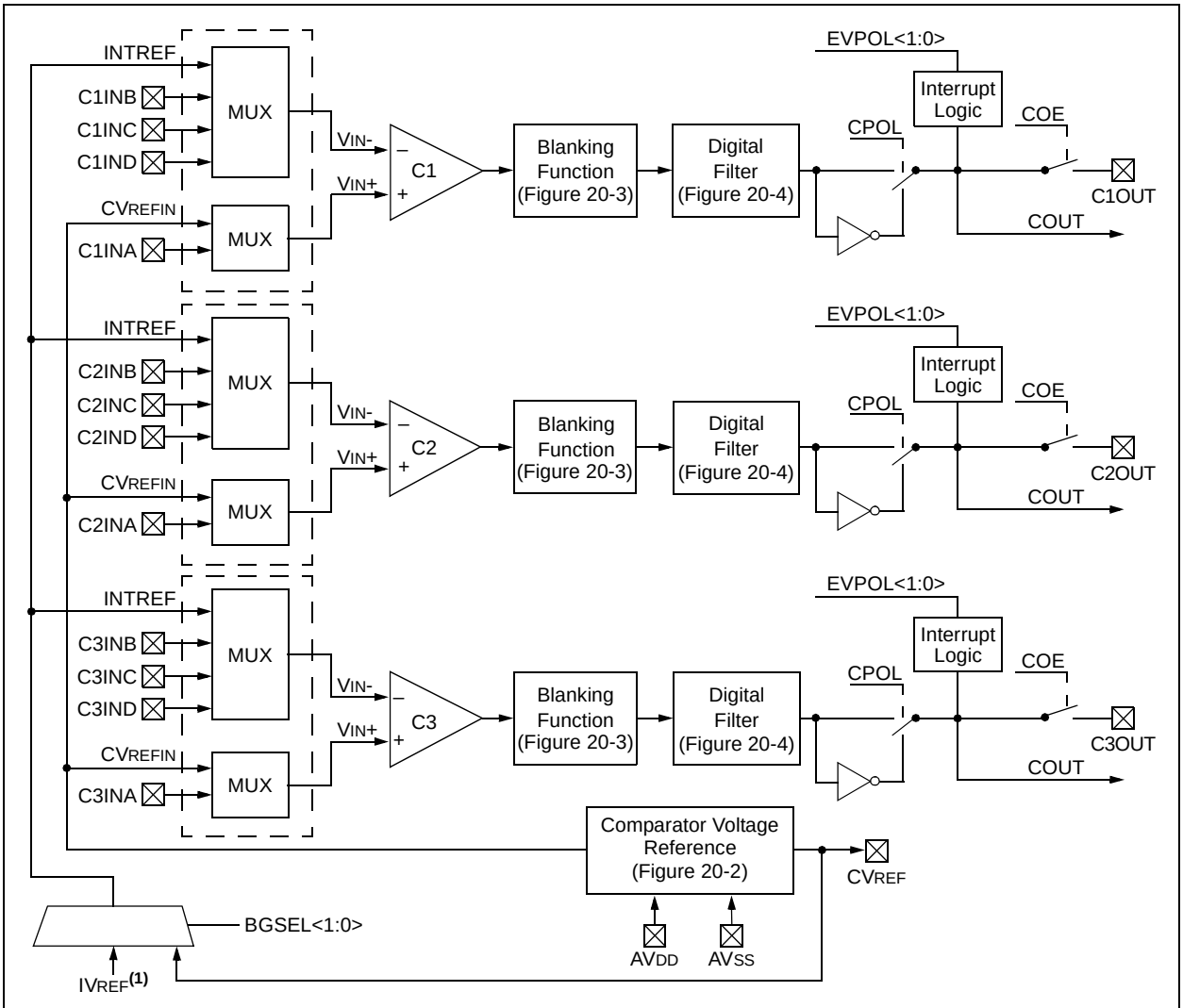
The comparator module provides three comparators that can be configured in different ways. As shown in Figure 20-1, individual comparator options are specified by the comparator module's Special Function Register (SFR) control bits.

These options allow users to:

- Select the edge for trigger and interrupt generation
- Select low-power control
- Configure the comparator voltage reference and band gap
- Configure output blanking and masking

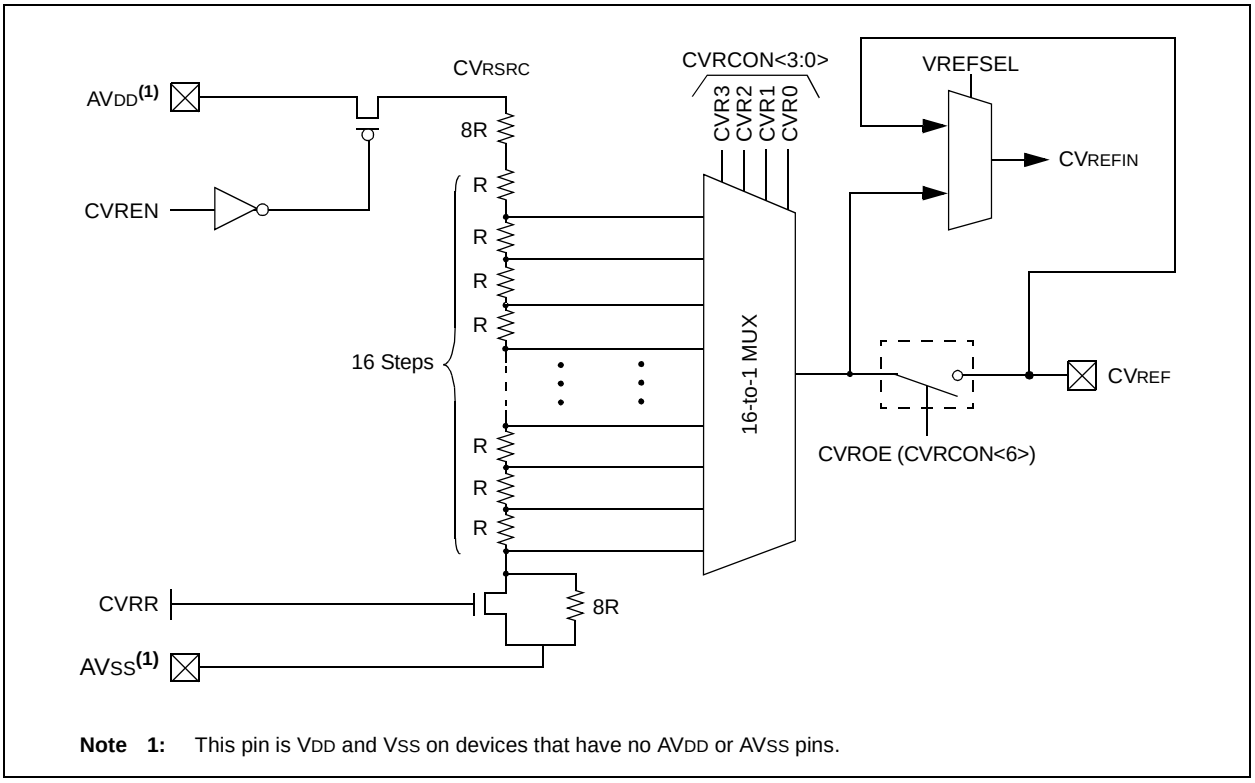
The comparator operating mode is determined by the input selections (i.e., whether the input voltage is compared to a second input voltage) to an internal voltage reference.

FIGURE 20-1: COMPARATOR I/O OPERATING MODES



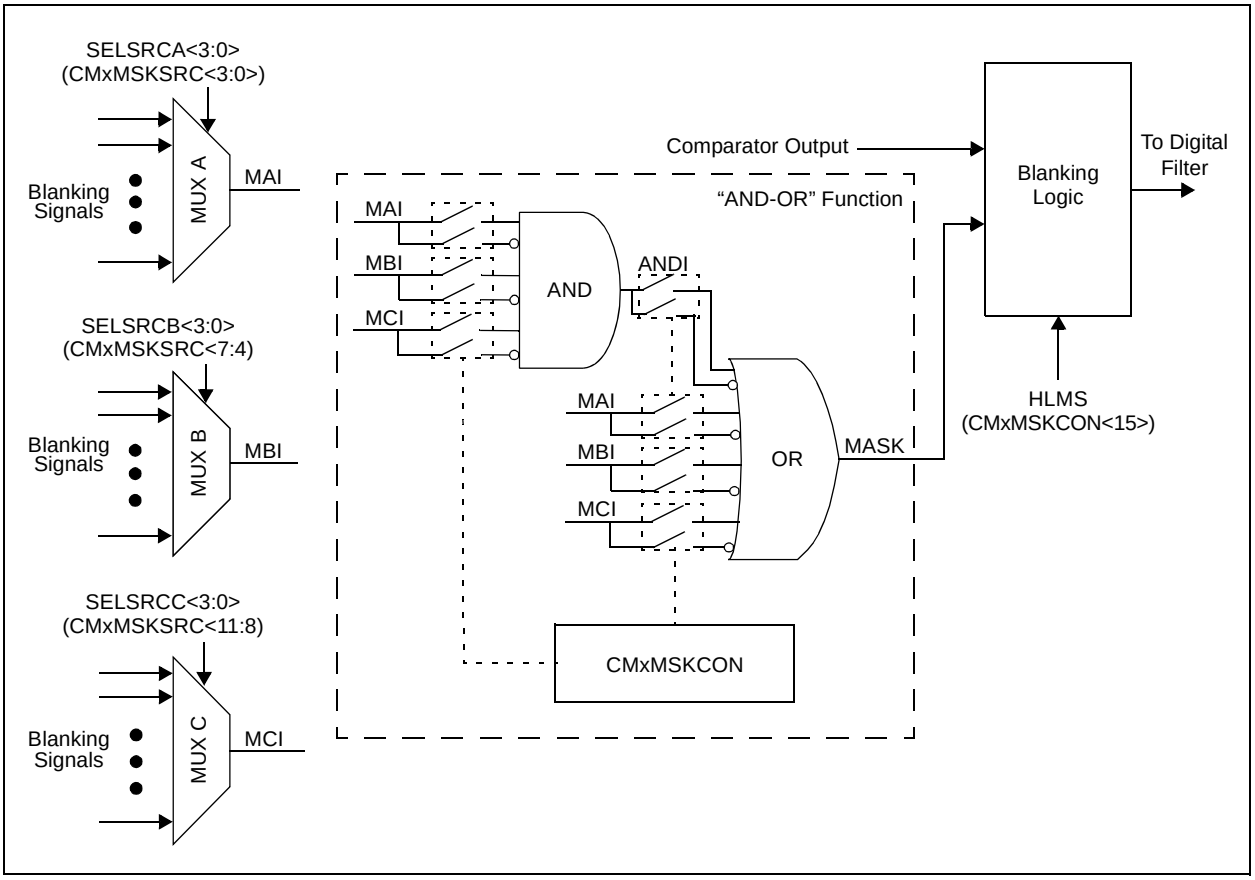
Note 1: This reference voltage is generated internally on the device. Refer to **Section 26.0 "Electrical Characteristics"** for the specified voltage range.

FIGURE 20-2: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



Note 1: This pin is VDD and VSS on devices that have no AVDD or AVSS pins.

FIGURE 20-3: USER-PROGRAMMABLE BLANKING FUNCTION BLOCK DIAGRAM



21.2 RTCC Control Registers

REGISTER 21-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER(1)

R/W-0	U-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0
RTCEN(2)	—	RTCWREN	RTCSYNC	HALFSEC(3)	RTCOE	RTCPTR1	RTCPTR0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CAL7	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **RTCEN:** RTCC Enable bit(2)
1 = RTCC module is enabled
0 = RTCC module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **RTCWREN:** RTCC Value Registers Write Enable bit
1 = RTCVALH and RTCVALL registers can be written to by the user
0 = RTCVALH and RTCVALL registers are locked out from being written to by the user

bit 12 **RTCSYNC:** RTCC Value Registers Read Synchronization bit
1 = RTCVALH, RTCVALL and ALCFGRPT registers can change while reading, due to a rollover ripple, resulting in an invalid data read. If the register is read twice and the results are the same data, the data can be assumed to be valid.
0 = RTCVALH, RTCVALL or ALCFGRPT registers can be read without concern over a rollover ripple

bit 11 **HALFSEC:** Half-Second Status bit(3)
1 = Second half period of a second
0 = First half period of a second

bit 10 **RTCOE:** RTCC Output Enable bit
1 = RTCC output is enabled
0 = RTCC output is disabled

bit 9-8 **RTCPTR<1:0>:** RTCC Value Register Window Pointer bits
Points to the corresponding RTCC Value registers when reading RTCVALH and RTCVALL registers; the RTCPTR<1:0> value decrements on every read or write of RTCVALH until it reaches '00'.
RTCVAL<15:8>:
00 = MINUTES
01 = WEEKDAY
10 = MONTH
11 = Reserved
RTCVAL<7:0>:
00 = SECONDS
01 = HOURS
10 = DAY
11 = YEAR

Note 1: The RCFGCAL register is only affected by a POR.
2: A write to the RTCEN bit is only allowed when RTCWREN = 1.
3: This bit is read-only; it is cleared to '0' on a write to the lower half of the MINSEC register.

25.11 Demonstration/Development Boards, Evaluation Kits and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

25.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

TABLE 26-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off, Clock On Base Current(2) – dsPIC33FJ16(GP/MC)10X Devices						
DC40d	0.4	1.0	mA	-40°C	3.3V	LPRC (32.768 kHz)(3)
DC40a	0.4	1.0	mA	+25°C		
DC40b	0.4	1.0	mA	+85°C		
DC40c	0.5	1.0	mA	+125°C		
DC41d	0.5	1.1	mA	-40°C	3.3V	1 MIPS(3)
DC41a	0.5	1.1	mA	+25°C		
DC41b	0.5	1.1	mA	+85°C		
DC41c	0.8	1.1	mA	+125°C		
DC42d	0.9	1.6	mA	-40°C	3.3V	4 MIPS(3)
DC42a	0.9	1.6	mA	+25°C		
DC42b	1.0	1.6	mA	+85°C		
DC42c	1.2	1.6	mA	+125°C		
DC43a	1.6	2.6	mA	+25°C	3.3V	10 MIPS(3)
DC43d	1.6	2.6	mA	-40°C		
DC43b	1.7	2.6	mA	+85°C		
DC43c	2	2.6	mA	+125°C		
DC44d	2.4	3.8	mA	-40°C	3.3V	16 MIPS(3)
DC44a	2.4	3.8	mA	+25°C		
DC44b	2.6	3.8	mA	+85°C		
DC44c	2.9	3.8	mA	+125°C		

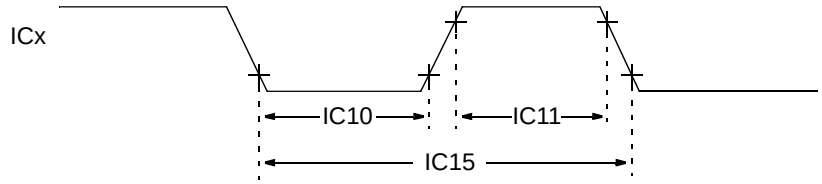
Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

2: Base Idle current is measured as follows:

- CPU core is off, oscillator is configured in EC mode, OSC1 is driven with external square wave from rail-to-rail
- CLKO is configured as an I/O input pin in the Configuration Word
- External Secondary Oscillator (SOSC) is disabled (i.e., SOSCO and SOSCI pins are configured as digital I/O inputs)
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- No peripheral modules are operating; however, every peripheral is being clocked (PMDx bits are all zeroed)

3: These parameters are characterized, but not tested in manufacturing.

FIGURE 26-6: INPUT CAPTURE x (ICx) TIMING CHARACTERISTICS



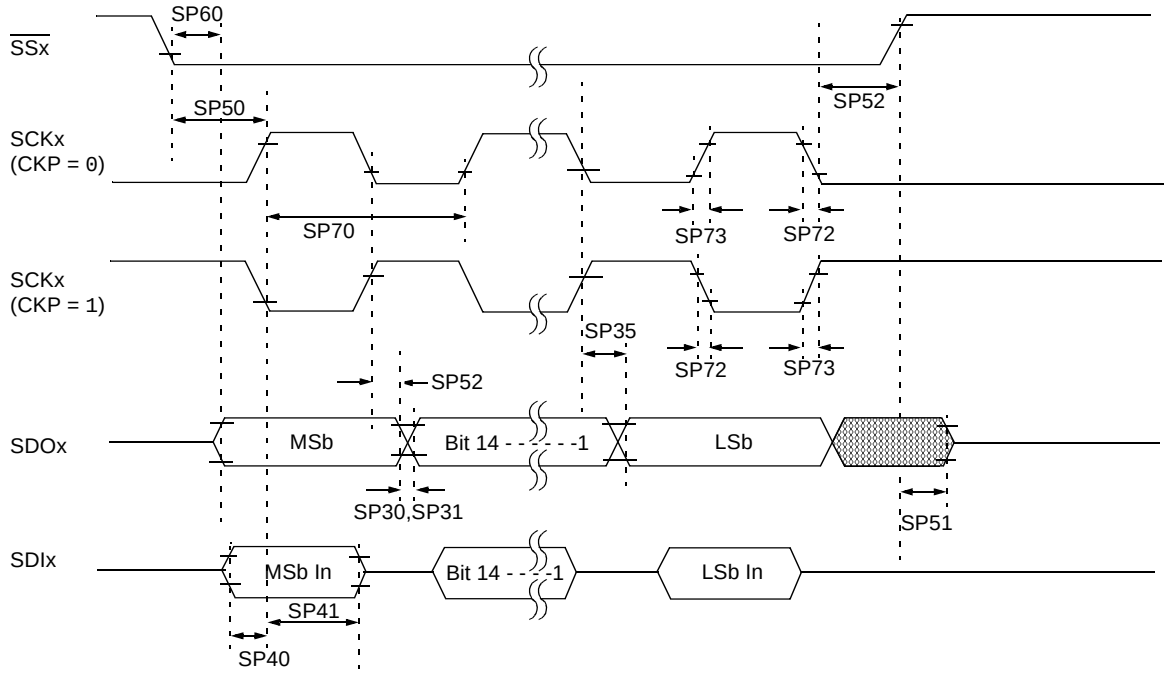
Note: Refer to Figure 26-1 for load conditions.

TABLE 26-25: INPUT CAPTURE x (ICx) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**		**Min**	**Max**	**Units**	**Conditions**
IC10	TccL	ICx Input Low Time	No Prescaler	0.5 TCY + 20	—	ns	
			With Prescaler	10	—	ns	
IC11	TccH	ICx Input High Time	No Prescaler	0.5 TCY + 20	—	ns	
			With Prescaler	10	—	ns	
IC15	TccP	ICx Input Period		(TCY + 40)/N	—	ns	N = prescale value (1, 4, 16)

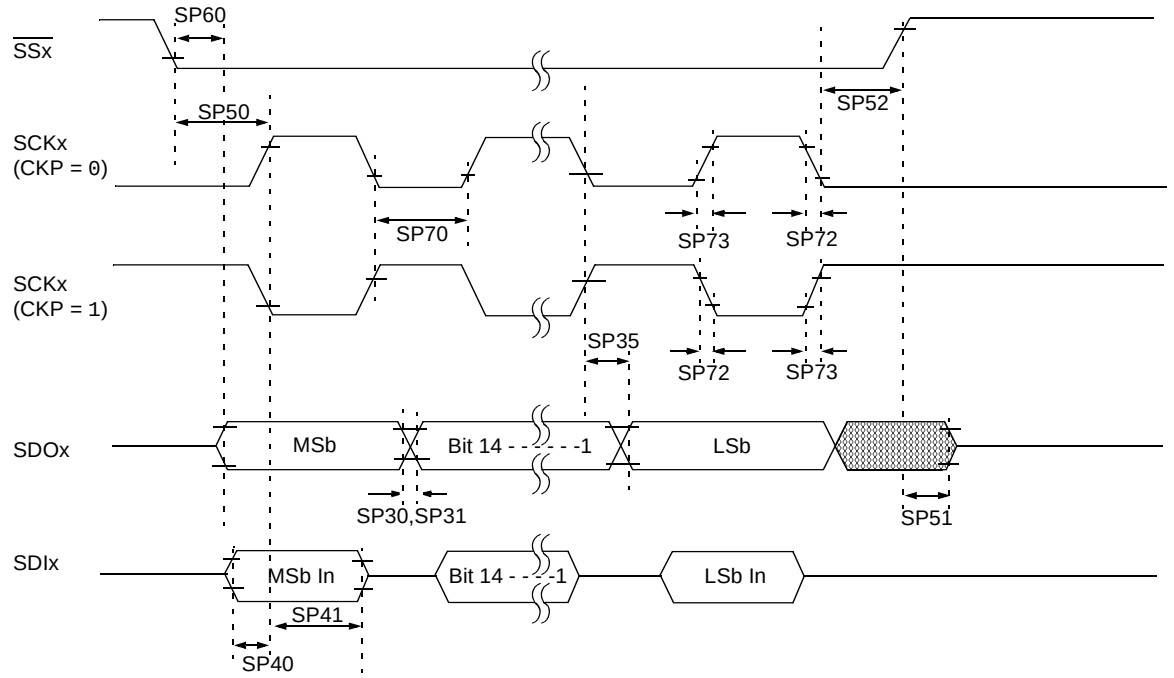
Note 1: These parameters are characterized by similarity, but are not tested in manufacturing.

FIGURE 26-16: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ16(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-23: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-41: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS FOR dsPIC33FJ32(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	50	ns	

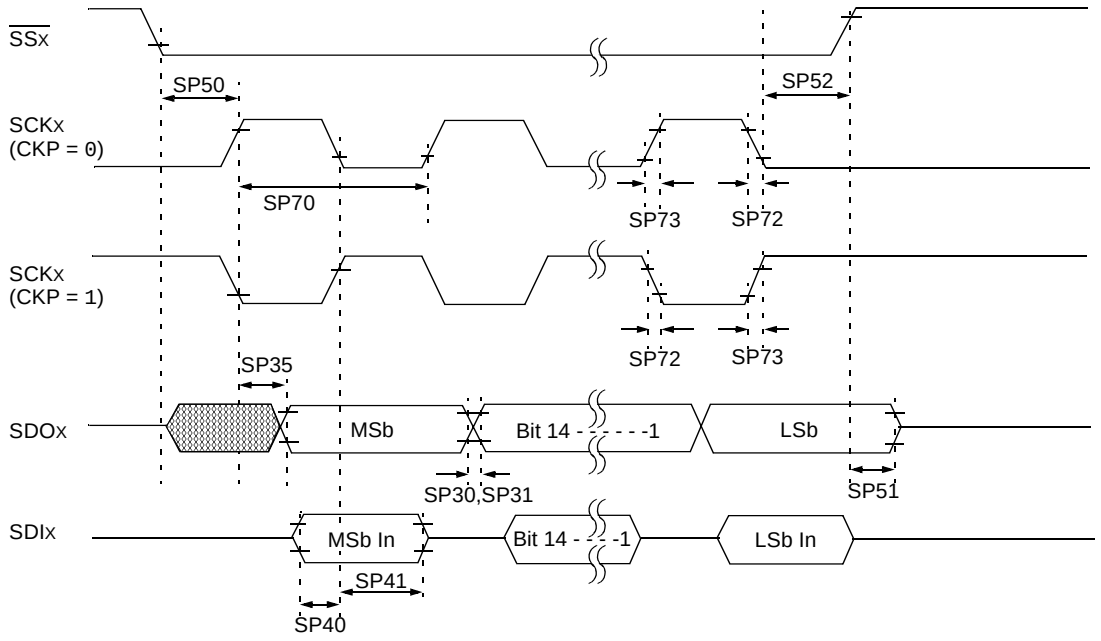
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCKx clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 26-26: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

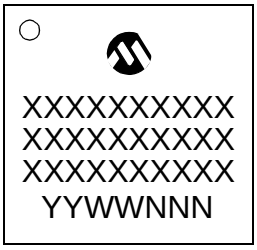
TABLE 26-46: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param.	**Symbol**	**Characteristic**		**Min**	**Max**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	µs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	µs	
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	µs	
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(1)	0	0.3	µs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.6	—	µs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	
			400 kHz mode	600	—	ns	
			1 MHz mode(1)	250		ns	
IS40	TAA:SCL	Output Valid from Clock	100 kHz mode	0	3500	ns	
			400 kHz mode	0	1000	ns	
			1 MHz mode(1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(1)	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	

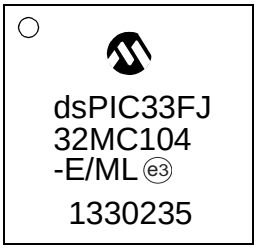
Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

28.1 Package Marking Information (Continued)

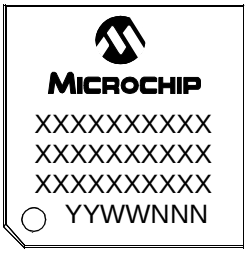
44-Lead QFN



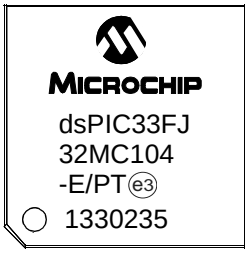
Example



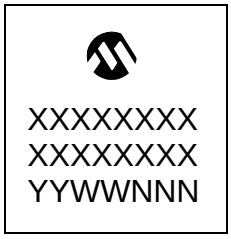
44-Lead TQFP



Example



44-Lead VTLA



Example

Revision D (April 2012)

This revision includes updates in support of the following new devices:

- dsPIC33FJ32GP101
- dsPIC33FJ32GP102
- dsPIC33FJ32GP104
- dsPIC33FJ32MC101
- dsPIC33FJ32MC102
- dsPIC33FJ32MC104

Also, where applicable, new sections were added to peripheral chapters that provide information and links to the related resources, as well as helpful tips. For examples, see **Section 18.1 "UART Helpful Tips"** and **Section 18.2 "UART Resources"**.

This revision includes text and formatting changes that were incorporated throughout the document.

All other major changes are referenced by their respective section in Table A-3.

TABLE A-3: MAJOR SECTION UPDATES

Section Name	Update Description
"16-Bit Digital Signal Controllers (up to 32-Kbyte Flash and 2-Kbyte SRAM)"	The content on the first page of this section was extensively reworked to provide the reader with the key features and functionality of this device family in an "at-a-glance" format. **TABLE 2: "dsPIC33FJ32(GP/MC)101/102/104 Device Features"** was added, which provides a feature overview of the new devices. All pin diagrams were updated (see **"Pin Diagrams"**).
Section 1.0 "Device Overview"	Updated the notes in the device family block diagram (see Figure 1-1). Updated the following pinout I/O descriptions (Table 1-1): • ANx • CNx • RAx • RCx • CVREFIN (formerly CVREF) Relocated **1.1 "Referenced Sources"** to the previous chapter (see **"Referenced Sources"**).
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Updated the Recommended Minimum Connection diagram (see Figure 2-1).
Section 4.0 "Memory Organization"	Updated the existing Program Memory Map (see Figure 4-1) and added the Program Memory Map for dsPIC33FJ16(GP/MC)101/102 Devices (see Figure 4-1). Updated the existing Data Memory Map (see Figure 4-4) and added the Data Memory Map for dsPIC33FJ32(GP/MC)101/102/104 Devices with 2-Kbyte RAM (see Figure 4-5). The following Special Function Register maps were updated or added: • TABLE 4-5: Change Notification Register Map for dsPIC33FJ32(GP/MC)104 Devices • TABLE 4-6: Interrupt Controller Register Map • TABLE 4-8: Timers Register Map for dsPIC33FJ32(GP/MC)10X Devices • TABLE 4-15: ADC1 Register Map for dsPIC33FJXX(GP/MC)101 Devices • TABLE 4-17: ADC1 Register Map for dsPIC33FJ32(GP/MC)104 Devices • TABLE 4-22: Peripheral Pin Select Input Register Map • TABLE 4-26: Peripheral Pin Select Output Register Map for dsPIC33FJ32(GP/MC)104 Devices • TABLE 4-28: PORTA Register Map for dsPIC33FJ32(GP/MC)101/102 Devices • TABLE 4-29: PORTA Register Map for dsPIC33FJ32(GP/MC)104 Devices • TABLE 4-36: PORTC Register Map for dsPIC33FJ32(GP/MC)104 Devices • TABLE 4-39: PMD Register Map